

N - CHANNEL ENHANCEMENT MODE FAST POWER MOS TRANSISTOR

| TYPE | V _{DSS} | R _{DS(on)} | I _D |
|------------|------------------|---------------------|----------------|
| STP4NA60 | 600 V | < 2.2 Ω | 4.3 A |
| STP4NA60FI | 600 V | < 2.2 Ω | 2.7 A |

- TYPICAL R_{DS(on)} = 1.85 Ω
- ± 30V GATE TO SOURCE VOLTAGE RATING
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C
- LOW INTRINSIC CAPACITANCES
- GATE CHARGE MINIMIZED
- REDUCED THRESHOLD VOLTAGE SPREAD

DESCRIPTION

This series of POWER MOSFETs represents the most advanced high voltage technology. The optimized cell layout coupled with a new proprietary edge termination concur to give the device low R_{DS(on)} and gate charge, unequalled ruggedness and superior switching performance.

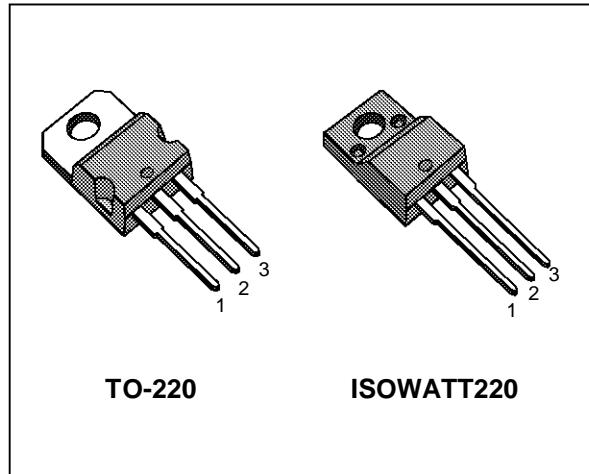
APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- DC-AC CONVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLIES AND MOTOR DRIVE

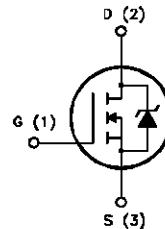
ABSOLUTE MAXIMUM RATINGS

| Symbol | Parameter | Value | | Unit |
|--------------------|---|------------|------------|------|
| | | STP4NA60 | STP4NA60FI | |
| V _{DS} | Drain-source Voltage (V _{GS} = 0) | 600 | 600 | V |
| V _{DGR} | Drain-gate Voltage (R _{GS} = 20 kΩ) | 600 | 600 | V |
| V _{GS} | Gate-source Voltage | ± 30 | ± 30 | V |
| I _D | Drain Current (continuous) at T _c = 25 °C | 4.3 | 2.7 | A |
| I _D | Drain Current (continuous) at T _c = 100 °C | 2.8 | 1.8 | A |
| I _{DM(•)} | Drain Current (pulsed) | 17.2 | 17.2 | A |
| P _{tot} | Total Dissipation at T _c = 25 °C | 100 | 40 | W |
| | Derating Factor | 0.8 | 0.32 | W/°C |
| V _{ISO} | Insulation Withstand Voltage (DC) | — | 2000 | V |
| T _{stg} | Storage Temperature | -65 to 150 | | °C |
| T _j | Max. Operating Junction Temperature | 150 | | °C |

(•) Pulse width limited by safe operating area



INTERNAL SCHEMATIC DIAGRAM



STP4NA60/FI

THERMAL DATA

| | | | TO-220 | ISOWATT220 | |
|---|---|------------|--------------------|------------|--------------------|
| R _{thj-case} | Thermal Resistance Junction-case | Max | 1.25 | 3.12 | °C/W |
| R _{thj-amb} R _{thc-sink} T ₁ | Thermal Resistance Junction-ambient Thermal Resistance Case-sink Maximum Lead Temperature For Soldering Purpose | Max Typ | 62.5 0.5 300 | | °C/W °C/W °C |

AVALANCHE CHARACTERISTICS

| Symbol | Parameter | Max Value | Unit |
|-----------------|--|-----------|------|
| I _{AR} | Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T _j max, δ < 1%) | 4.3 | A |
| E _{AS} | Single Pulse Avalanche Energy (starting T _j = 25 °C, I _D = I _{AR} , V _{DD} = 50 V) | 95 | mJ |
| E _{AR} | Repetitive Avalanche Energy (pulse width limited by T _j max, δ < 1%) | 4 | mJ |
| I _{AR} | Avalanche Current, Repetitive or Not-Repetitive (T _c = 100 °C, pulse width limited by T _j max, δ < 1%) | 2.8 | A |

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|----------------------|---|--|------|------|-----------|----------|
| V _{(BR)DSS} | Drain-source Breakdown Voltage | I _D = 250 μA V _{GS} = 0 | 600 | | | V |
| I _{dss} | Zero Gate Voltage Drain Current (V _{GS} = 0) | V _{DS} = Max Rating V _{DS} = Max Rating x 0.8 T _c = 125 °C | | | 25 250 | μA μA |
| I _{GSS} | Gate-body Leakage Current (V _{DS} = 0) | V _{GS} = ± 30 V | | | ± 100 | nA |

ON (*)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------------|-----------------------------------|--|------|------|------|------|
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} I _D = 250 μA | 2.25 | 3 | 3.75 | V |
| R _{D(on)} | Static Drain-source On Resistance | V _{GS} = 10V I _D = 2 A | | 1.85 | 2.2 | Ω |
| I _{D(on)} | On State Drain Current | V _{DS} > I _{D(on)} x R _{D(on)max} V _{GS} = 10 V | 4.3 | | | A |

DYNAMIC

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|--|---|---|------|------------------|------------------|----------------|
| g _{fs} (*) | Forward Transconductance | V _{DS} > I _{D(on)} x R _{D(on)max} I _D = 2 A | 2.5 | 3.7 | | S |
| C _{iss} C _{oss} C _{rss} | Input Capacitance Output Capacitance Reverse Transfer Capacitance | V _{DS} = 25 V f = 1 MHz V _{GS} = 0 | | 700 100 24 | 910 130 35 | pF pF pF |

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------|--|---|------|---------------|----------|------------------------|
| $t_{d(on)}$ t_r | Turn-on Time Rise Time | $V_{DD} = 300 \text{ V}$ $I_D = 2 \text{ A}$ $R_G = 47 \Omega$ $V_{GS} = 10 \text{ V}$ (see test circuit, figure 3) | | 23 60 | 35 85 | ns ns |
| $(di/dt)_{on}$ | Turn-on Current Slope | $V_{DD} = 480 \text{ V}$ $I_D = 4 \text{ A}$ $R_G = 47 \Omega$ $V_{GS} = 10 \text{ V}$ (see test circuit, figure 5) | | 185 | | $\text{A}/\mu\text{s}$ |
| Q_g Q_{gs} Q_{gd} | Total Gate Charge Gate-Source Charge Gate-Drain Charge | $V_{DD} = 480 \text{ V}$ $I_D = 2 \text{ A}$ $V_{GS} = 10 \text{ V}$ | | 32 7 14 | 45 | nC nC nC |

SWITCHING OFF

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------------------------|---|---|------|----------------|----------------|----------------|
| $t_{r(Voff)}$ t_f t_c | Off-voltage Rise Time Fall Time Cross-over Time | $V_{DD} = 480 \text{ V}$ $I_D = 4 \text{ A}$ $R_G = 47 \Omega$ $V_{GS} = 10 \text{ V}$ (see test circuit, figure 5) | | 45 17 70 | 60 25 95 | ns ns ns |

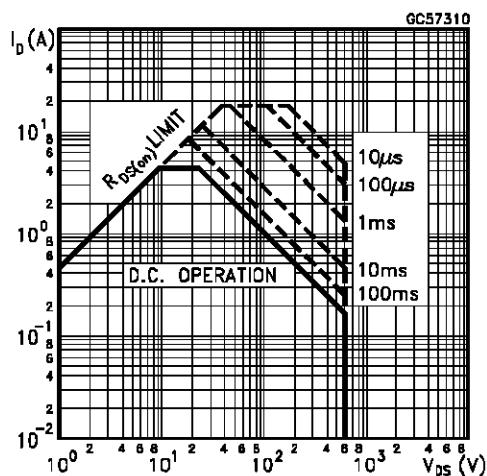
SOURCE DRAIN DIODE

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-----------------------------------|--|--|------|----------------|-------------|--------------------------|
| I_{SD} $I_{SDM}(\bullet)$ | Source-drain Current Source-drain Current (pulsed) | | | | 4.3 17.2 | A A |
| $V_{SD} (\ast)$ | Forward On Voltage | $I_{SD} = 4.3 \text{ A}$ $V_{GS} = 0$ | | | 1.6 | V |
| t_{rr} Q_{rr} I_{RRM} | Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current | $I_{SD} = 4 \text{ A}$ $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 100 \text{ V}$ $T_j = 150^\circ\text{C}$ (see test circuit, figure 5) | | 480 6 25 | | ns μC A |

(*) Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %

(*) Pulse width limited by safe operating area

Safe Operating Areas for TO-220



Safe Operating Areas for ISOWATT220

